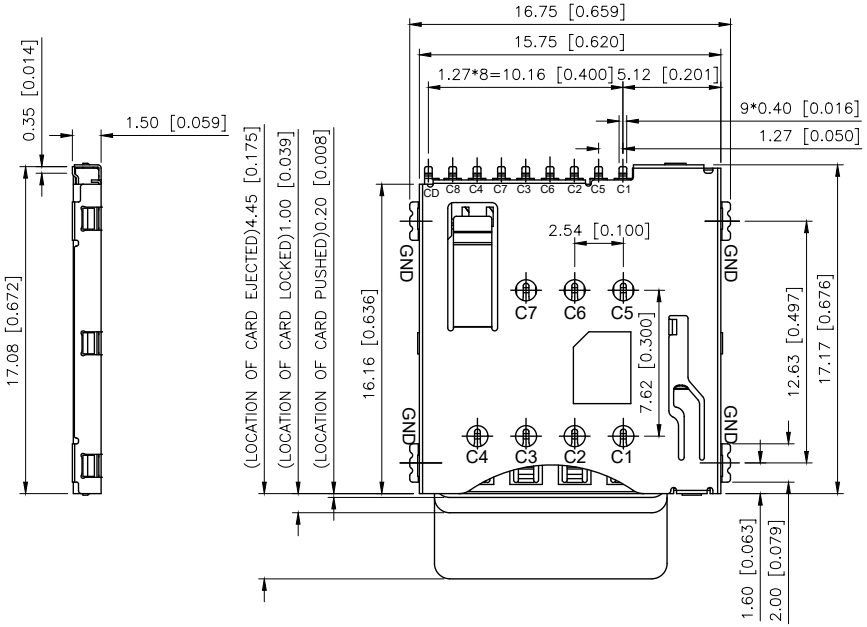
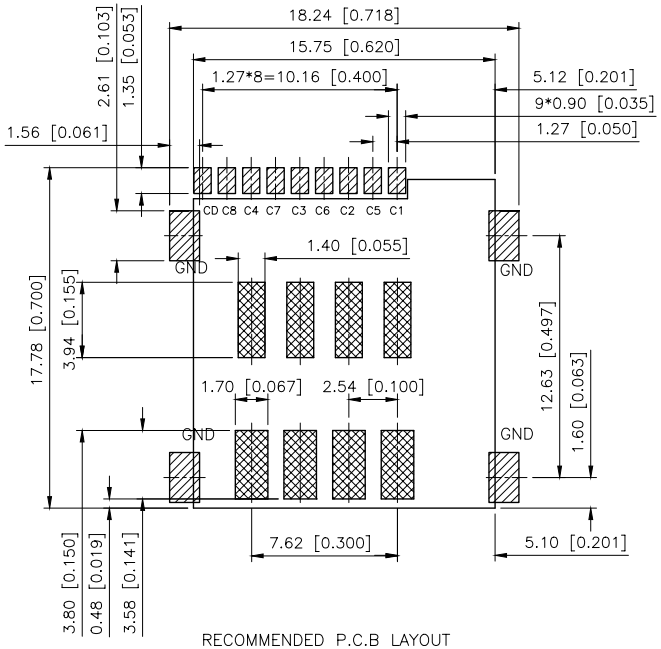
REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.16	阿树



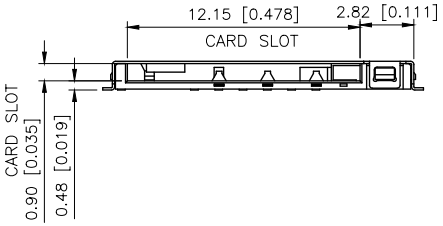


RECOMMENDED P.C.B LAYOUT

COMPONENT SIDE(TOLERANCE ±0.05)

PAD AREA

KEEP OUT AREA



3FF SIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions:15.75LX17.17WX1.50H mm

Weight:Approx 0.4±0.1g

Durability:1500 cycles min.

2.Electrical Characteristics

Contact resistance;

Date Contact:150mΩ max

CD Switch:500mΩ max

Insulation resistance:>1000MΩ/500V DC

3.Solderability

Vapor phase:215°C,30sec.Max

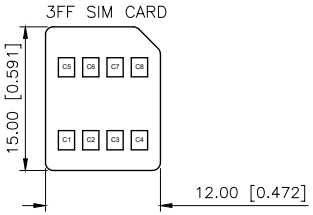
IR reflow:250°C,5sec.Max

Manual soldering:370°C,3sec.Max

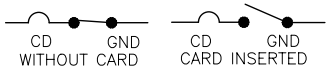
4.Environmental Characteristics

Operating temperature:−40°C~+85°C

Operating humidity:10%~+95%RH



ELECTRIC FUNCTION	DETECT SWITCH
WITHOUT CARD	CLOSED
CARD INSERTED	OPEN



SWITCH OPERATION DIAGRAM

ITEM	PART NAME	Q'TY	MATERIAL	FINISHING
1	HOUSING	1	HI−TEMP.PLASIC	Black UL94V−0
2	TERMINAL	9	COPPER ALLOY	Contact area:Gold plated
3	CD SWITCH	1	COPPER ALLOY	Contact area:Gold plated
4	SHELL	1	SUS	SMT area:Gold plated
5	SPRING	1	SWP	
6	HEART CAM	1	HI−TEMP.PLASIC	Black UL94V−0
7	CAM PIN	1	SUS	

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERAuCES	

XKB Connection 星创

DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKSIM−1511B−P9
APPROVED		SIZE: A4	DWG NO.: X−XKSIM−1511B−P9

XKB INDUSTRIAL PRECISION CO.,LIMITED

SCALE	PAGE	REVISION
N/A	1/1	A1

www.helloxkb.com www.helloxkb.cn www.xk-dg.cn